

Appl. No. 10/059,700  
Reply to Examiner's Office Communication dated February 14, 2006

**IN THE CLAIMS:**

1. (Canceled)
2. (Currently Amended) The method as recited in ~~Claim 1, further~~ Claim 3, further comprising forming a SAW transducer on each of said SAW identification tags.
3. (Previously Presented) A method of manufacturing piezoelectric wafers of surface acoustic wave (SAW) identification tags, comprising:
  - using a master reticle to form, on each of said piezoelectric wafers, wafer-independent patterns that encode digits of the first significance for said SAW identification tags; and
  - using different ones of a library of coding reticles to form, on each of said piezoelectric wafers, wafer-dependent patterns that encode digits of the second significance for said SAW identification tags, said wafer-independent and wafer-dependent patterns composed of reflectors distributed among a group of slots arranged by both pulse position and by phase position, said reflectors encoding said digits of the first significance and said digits of the second significance.
4. (Original) The method as recited in Claim 3 wherein said reflectors are structures that reflect a surface acoustic wave.
5. (Original) The method as recited in Claim 3 further comprising forming a framing reflector on said SAW identification tags, said framing reflector located between said SAW transducer and said group of slots.
6. (Original) The method as recited in Claim 3 further comprising forming a plurality of said

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groups separated by dead spaces.

7. (Original) The method as recited in Claim 6 wherein said plurality of groups is at least twelve.

8. (Original) The method as recited in Claim 4 wherein at least some of said reflectors are single strips of conductive metal.

9. (Original) The method as recited in Claim 3 further comprising forming an end reflector on said SAW identification tags.

Claims 10-31 (Canceled)